

## Features

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Lead Free By Design/RoHS Compliant (Note 3)
- "Green" Device (Note 4)
- Qualified to AEC-Q101 Standards for High Reliability



DMG8822UTS

D2

**DUAL N-CHANNEL ENHANCEMENT MODE MOSFET** 

#### **Mechanical Data**

- Case: TSSOP-8L
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminal Connections: See Diagram Below

D1

- Marking Information: See Page 4
- Ordering Information: See Page 4

G1

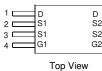
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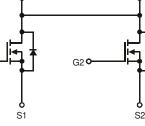
• Weight: 0.039 grams (approximate)

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Internal Schematic

## Maximum Ratings @TA = 25°C unless otherwise specified

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V <sub>DSS</sub>	20	V
Gate-Source Voltage			V <sub>GSS</sub>	±8	V
Continuous Drain Current (Note 1)	Steady State	T <sub>A</sub> = 25°C T <sub>A</sub> = 70°C	ID	4.9 3.9	A
Pulsed Drain Current (Note 2)			I <sub>DM</sub>	31	А

Pin Configuration

# **Thermal Characteristics**

Notes:

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	PD	0.87	W
Thermal Resistance, Junction to Ambient $@T_A = 25^{\circ}C$	R <sub>0JA</sub>	143	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

1. Device mounted on FR-4 PCB with minimum recommended pad layout.

2. Repetitive rating, pulse width limited by junction temperature.

3. No purposefully added lead.

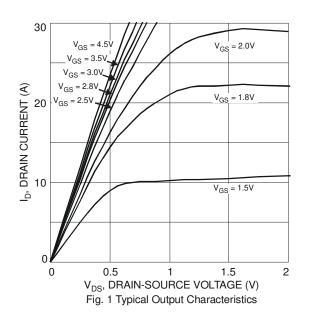
4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.

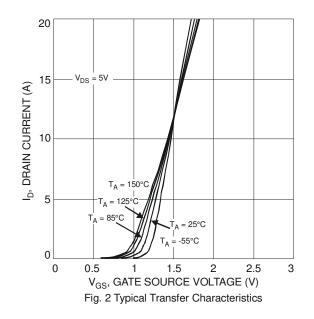


# Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 5)		-			-		
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	-	-	V	$V_{GS} = 0V, I_D = 250 \mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	-	-	1.0	μA	$V_{DS} = 20V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	-	-	±100	nA	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 5)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.5	-	0.9	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
		-	19 22 28	25 29 37	mΩ	$V_{GS} = 4.5V, I_D = 8.2A$	
Static Drain-Source On-Resistance	R <sub>DS (ON)</sub>					$V_{GS} = 2.5V, I_D = 3.3A$	
						V <sub>GS</sub> = 1.8V, I <sub>D</sub> = 2.0A	
Forward Transfer Admittance	Y <sub>fs</sub>	-	7	-	S	$V_{DS} = 10V, I_D = 4A$	
Diodes Forward Voltage	V <sub>SD</sub>	-	0.7	0.9	V	ls = 2.25A, V <sub>GS</sub> = 0V	
DYNAMIC CHARACTERISTICS (Note 6)							
Input Capacitance	C <sub>iss</sub>	-	841	-	pF	$-V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz	
Output Capacitance	Coss	-	88	-	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>	-	81	-	pF		
Gate Resistance	Ra	-	1.24	-	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	
SWITCHING CHARACTERISTICS			_				
Total Gate Charge	Qg	-	9.6	-	nC	$V_{GS} = 4.5V, V_{DS} = 10V,$ $I_D = 8.2A$	
Gate-Source Charge	Q <sub>gs</sub>	-	1.4	-	nC		
Gate-Drain Charge	Q <sub>gd</sub>	-	2.1	-	nC		
Turn-On Delay Time	t <sub>D(on)</sub>	-	7.8	-	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$ $R_L = 10\Omega, R_G = 6\Omega$	
Turn-On Rise Time	tr	-	21.1	-	ns		
Turn-Off Delay Time	t <sub>D(off)</sub>	-	38.6	-	ns		
Turn-Off Fall Time	tr	-	10.1	-	ns	7	

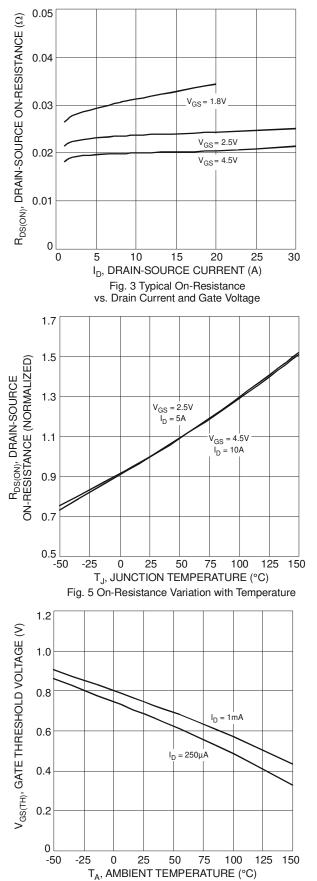
Notes: 5. Short duration pulse test used to minimize self-heating effects. 6. Guaranteed by design. Not subject to production testing.

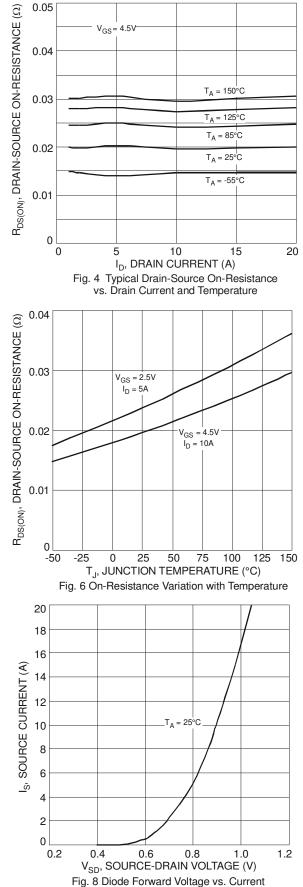








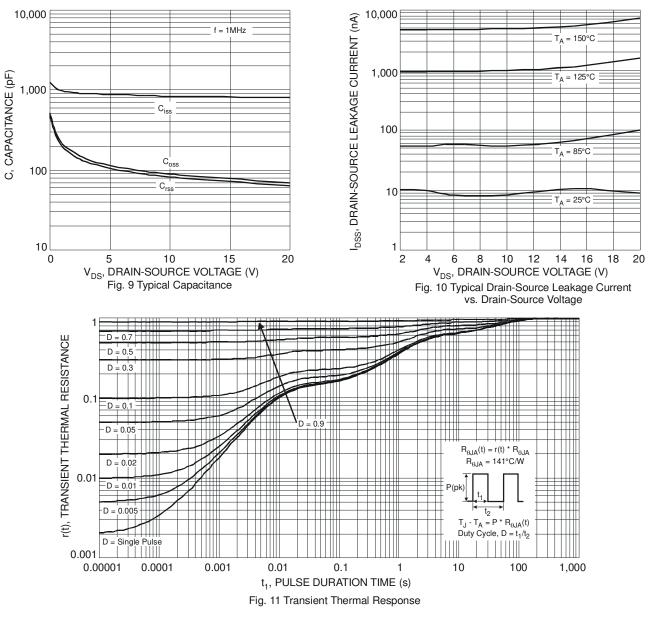




DMG8822UTS Document number: DS31798 Rev. 2 - 2



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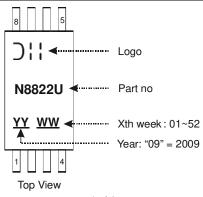


## Ordering Information (Note 7)

Part Number	Case	Packaging
DMG8822UTS-13	TSSOP-8L	2500 / Tape & Reel

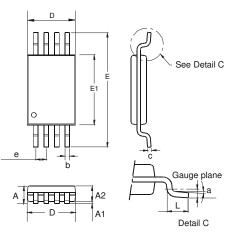
Notes: 7. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

### **Marking Information**



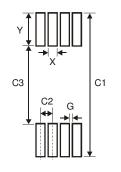


## **Package Outline Dimensions**



TSSOP-8L					
Dim	Min	Max	Тур		
а	0.09	-	-		
Α	-	1.20	-		
A1	0.05	0.15	_		
A2	0.825	1.025	0.925		
b	0.19	0.30	-		
С	0.09	0.20	-		
D	2.90	3.10	3.025		
е	-	-	0.65		
Е	_	_	6.40		
E1	4.30	4.50	4.425		
L	0.45	0.75	0.60		
All Dimensions in mm					

# Suggested Pad Layout



Dimensions	Value (in mm)
Х	0.45
Y	1.78
C1	7.72
C2	0.65
C3	4.16
G	0.20



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